



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	11/26/2014
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MYND*UA29AB5	A	SA1A	11/26/2014
Amount	UoM	Unit type	ST ECOPACK Grade	
44.000	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	4X4X1.0	33	flat	
Comment	Package: VFQFPN 4x4x1.0 24 PITCH 0.5; MD valid for LNBH26PQR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MYND*UA29AB5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other Inorganic Material	4.045	mg	Supplier	Silicon Die	Si	7440-21-3		3.831	mg	947095	87068
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.047	mg	11619	1068
Silicon Die				supplier	metallization	Tungsten (W)	7440-33-7		0.037	mg	9147	841
Silicon Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.01	mg	2472	227
Silicon Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.08	mg	19778	1818
Silicon Die				supplier	passivation	Gamma-butyrolactone	96-48-0		0.027	mg	6675	614
Silicon Die				supplier	passivation	Polyhydroxyamide	55295-98-2		0.012	mg	2967	273
Silicon Die				supplier	passivation	Alcoxysilane	proprietary		0.001	mg	247	23
Leadframe	Copper and its alloy	13.791	mg	Supplier	Alloy	Copper	7440-50-8		13.32	mg	965847	302727
Leadframe				Supplier	Alloy	Iron	7439-89-6		0.311	mg	22551	7068
Leadframe				Supplier	Alloy	Lead	7439-92-1		0.001	mg	73	23
Leadframe				Supplier	Alloy	Phosphorus	7723-14-0		0.003	mg	218	68
Leadframe				Supplier	Alloy	Zinc	7440-66-6		0.018	mg	1305	409
Leadframe				Supplier	Alloy	Silver	7440-22-4		0.138	mg	10007	9136
Die Attach	Other Organic Material	0.122	mg	Supplier	Glue	Silver	7440-22-4		0.097	mg	795082	2205
Die Attach				Supplier	Glue	methylene diacrylate	42594-17-2		0.012	mg	98361	273
Die Attach				Supplier	Glue	Dicyclopentyloxyethyl methacrylate	68586-19-6		0.004	mg	32787	91
Die Attach				Supplier	Glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.004	mg	32787	91
Die Attach				Supplier	Glue	Palladium (Pd)	7440-05-3		0.004	mg	32787	91
Die Attach				Supplier	Glue	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.001	mg	8197	23
Bonding	Other Inorganic Material	0.156	mg	Supplier	Bonding Wire	Au	7440-57-5		0.156	mg	1000000	3545
Encapsulation	Other Organic Material	25.276	mg	Supplier	Molding Compound	Silica Fused	60676-86-0		23.669	mg	936422	537932
Encapsulation				Supplier	Molding Compound	Epoxy Resin	Proprietary		0.765	mg	30266	17386
Encapsulation				Supplier	Molding Compound	Phenol Resin	Proprietary		0.765	mg	30266	17386
Encapsulation				Supplier	Molding Compound	Carbon Black	1333-86-4		0.077	mg	3046	1750
Finishing	Other Inorganic Material	0.61	mg	Supplier	Connection coating	Sn	7440-31-5		0.61	mg	1000000	13864